

**UNITED STATES PATENT APPLICATION**

**FOR**

**AC COUPLED LINE TESTING USING  
BOUNDARY SCAN TEST METHODOLOGY**

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## SPECIFICATION

### TITLE OF THE INVENTION

5 AC COUPLED LINE TESTING USING  
BOUNDARY SCAN TEST METHODOLOGY

### FIELD OF THE INVENTION

10 The present invention relates generally to boundary scan testing of  
interconnections between integrated circuits. More specifically, the present invention  
relates to AC coupled boundary scan testing.

### BACKGROUND OF THE INVENTION

15 Electronic systems generally include at least one printed circuit board (PCB)  
containing one or more integrated circuit (IC) chips or ICs. ICs typically include  
input/output (I/O) pins which may be coupled to various interconnects of the PCB.

Testing performance of electronic systems which include PCBs and ICs typically requires  
testing at multiple levels including at the chip level, at the board level, and at the system  
level. Testing at the board level includes testing interconnects of the PCB. Testing at the  
20 system level requires analysis of interconnections between and among the ICs, the PCBs,  
and other devices both on and off the PCB.

To enhance testability at the board level as well as at the system level, a common design practice at the chip level is to incorporate boundary scan test logic into an IC in accordance with IEEE Standard 1149.1. 1149.1 specifies the function of JTAG logic, which is named for the Joint Test Action Group, for control of boundary scan testing.

5 Two basic elements of an IC are a core logic and the I/O pins. In accordance with 1149.1, boundary scan cells (BSCs) are inserted between the core logic and the I/O pins of the IC. BSCs are typically inserted for all I/O pins of the plurality of ICs on the PCB and may be used to test the integrity of the interconnections between the plurality of ICs.

10 Each IC may be controlled by boundary scan logic, in accordance with 1149.1, to operate either in a system mode or in a JTAG test mode. In the system mode, system data signals relating to core functions of the IC are passed through the I/O pins to and from devices external to the IC. In the JTAG test mode, test data are provided by the boundary scan chain for the purpose of testing interconnections between the IC and  
15 devices external to the IC. The boundary scan logic also provides test control signals which include mode signals, shift signals, clock signals, and update signals, among others, each of which is well known. The shift control signal instructions include a bypass instruction, a sample instruction, and a cross test instruction. The cross test instruction controls BSCs to perform a boundary scan test among the various ICs.

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The IC further includes a test data input (TDI) demultiplexer, a test data output (TDO) multiplexer, a bypass register, an instruction register, an identification register, and a test access port (TAP) controller. The TDI demultiplexer includes an input coupled

to receive a test data signal from the boundary scan logic which is typically external to the IC. The TDI demultiplexer includes a first output coupled to a TDI input of a first BSC of the plurality of BSCs in the IC. Each of the BSCs includes a TDI input and a TDO output. Each of BSCs is connected serially from a TDO output to a TDI input to propagate test data signals from one BSC to the next BSC in the chain. The TDI demultiplexer further includes a second output coupled to an input of the core logic, a third output coupled to an input of the bypass register; a fourth output coupled to an input of the instruction register; and a fifth output coupled to an input of the identification register.

The TDO multiplexer includes an output which is coupled to provide a test data signal to another IC or to the boundary scan logic. The TDO multiplexer further includes: a first input coupled to a TDO output of a last BSC of the plurality of BSCs in the IC, a second input coupled to an output of the core logic; a third input coupled to an output of the bypass register; a fourth input coupled to an output of the instruction register, and a fifth input coupled to an output of the identification register. The identification register includes inputs coupled to outputs of the TAP controller. The TAP controller includes inputs coupled to receive a *TMS* signal, a *TCK* signal, and a *TRST* signal from the boundary scan logic.

In general, there are three possible I/O structures for an IC including a two-state I/O structure, a three-state I/O structure, and a bi-directional I/O structure. Each of the three I/O structures provides coupling between the core logic and at least one I/O pin.

Any or all of the I/O structures may be used in an IC depending on the particular circumstances. The two-state I/O structure includes a two-state output buffer having an input and an output. The input of the two-state output buffer is coupled to a system data output of the core logic. The output of the two-state output buffer is coupled to an I/O pin. The three-state I/O structure includes a three-state output buffer having an input, an output, and a control input. The input of the three-state output buffer is coupled to a system data output of the core logic. The output of the three-state output buffer is coupled to an I/O pin. The control input of the three-state output buffer is coupled to a three-state system control signal output line of the core logic. The bi-directional I/O structure includes a bi-directional buffer. The bi-directional buffer includes an output buffer element having an input, an output, and a control input and an input buffer element having an input and an output. The control input of the output buffer element is coupled to a bi-directional control signal output line of the core logic. The input of the output buffer element is coupled to a system data output of the core logic. The output of the input buffer element is coupled to a system data received input of the core logic. The output of the output buffer element and the input of the input buffer element are coupled together with an I/O pin.

According to conventional methods and apparatus for boundary scan testing, the BSCs are inserted into the I/O structures between the buffers and the core logic. For a two-state output structure, a BSC is inserted between the core logic and the input of the two-state output buffer. For a three-state output structure, a BSC is inserted between the system data output of the core logic and the input of the three-state output buffer. Also, a

BSC is inserted between the three-state control signal output line of the core logic and the control input of the three-state output buffer. For a bi-directional output structure, a BSC is inserted between the system control signal output line of the core logic and the bi-directional output buffer. Also, a bi-directional BSC is inserted between the core logic and the bi-directional output buffer.

Turning first to FIG. 1, a detailed logic block diagram of a prior art BSC 10 is shown. The BSC 10 includes a boundary scan mode multiplexer (mode multiplexer) 12; a shift multiplexer 14, a data shift/capture register 16, and an update data register 18. The mode multiplexer 12 and the shift multiplexer 14 each have a system input (0), an update input (1), an output, and a select line. The data shift/capture register 16 and the update data register 18 each have a data input (D), a clock input (CLK), a normal output (Q), and an inverted output (Q bar or not Q).

The BSC 10 includes a system data input (SDI) line for receiving system signals including system data signals and system control signals from the system signal output lines, including the system data signal output lines and the system control signal output lines, of the core logic. If the BSC 10 is used for control purposes, the SDI line may receive a system control signal from the core logic. If the BSC 10 is used for output, the SDI line may receive a system data signal from the core logic. If the BSC 10 is used for an input, the SDI line becomes a system data received input (SDRI) line for receiving signals from the I/O pin through an input buffer. The BSC 10 also includes a system data output (SDO) line for transmitting signals through an output buffer to the I/O pin. If the

BSC 10 is used for an input, the SDO line becomes a system data received output (SDRO) line for transmitting signals to the core logic. The SDI line and the SDO line complete the circuit between the core logic and the I/O structure that was bisected by the insertion of the BSC.

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For control of the mode of operation by the boundary scan logic and for various test inputs from the boundary scan logic, the BSC 10 further includes a number of JTAG lines. Part or all of these lines taken collectively are sometimes referred to as forming a JTAG bus. The primary JTAG lines are a TDI line which may receive a *TDI* signal from the boundary scan logic either directly or via another BSC and a TDO line for providing a *TDO* signal to the boundary scan logic either directly or via another BSC. These two lines are common to all types of BSCs as they are used to form the chain of BSCs. The JTAG lines further include a *ShiftDR* signal input line, a *ClockDR* signal input line, an *UpdateDR* signal input line, and a *Mode* signal input line. Each line is coupled to receive the corresponding signal from the boundary scan logic. The various lines and circuit elements are coupled to one another as shown.

Turning now to FIG. 2, a detailed logic block diagram of a prior art bi-directional BSC 20 is shown. The bi-directional BSC 20 includes a bi-directional system multiplexer 22, a direction control multiplexer 24, a bi-directional shift control multiplexer 26, a bi-directional data shift/capture register 28, and a bi-directional update data register 30. The bi-directional system multiplexer 22, the direction control multiplexer 24, and the bi-directional shift control multiplexer 26 each have a system

input (0), an update input (1), an output, and a select line. The bi-directional data shift/capture register 28 and the bi-directional update data register 30 each have a data input (D), a clock input (CLK), a normal output (Q), and an inverted output (Q bar or not Q).

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Since the bi-directional BSC 20 serves both as an output and an input, it includes an SDI line, an SDO line, an SDRI line, and an SDRO line as described above.

Similarly, the bi-directional BSC 20 includes a TDI line, a TDO line, a *ShiftDR* signal input line, a *ClockDR* signal input line, an *UpdateDR* signal input line, and a *Mode* signal input line. In addition, the bi-directional BSC 20 includes a *DIRCTL* signal input line. Each line is coupled to receive the corresponding signal from the boundary scan logic. The various lines and circuit elements are coupled to one another as shown.

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IEEE Standard 1149.1 was first adopted in 1990. It has been widely used and has proved to be very successful. 1149.1 has been amended once to improve it. However, 1149.1 does not address all situations and design practices. One such practice is the inclusion of capacitive coupling in the interconnections between ICs. A capacitor is added either to the connection between the ICs or to one, the other, or both of the I/O pins of the ICs or the PCBs with connectors. The capacitor is designed to reduce noise and block unwanted common mode voltage differences in the interconnection. For discussion, this will be referred to alternatively as either being AC coupled or DC de-coupled.



Turning now to FIG. 3, a block diagram of ten possible combinations of DC and AC coupled interconnections between two devices is shown. The choice of which of the combinations shown that are actually used depends on the circumstances. Because of the capacitor, the value of a signal at the receiving end of the interconnection is no longer the same as the value at the driving end. The result is that conventional 1149.1 testing becomes impractical on AC coupled interconnections. One will note that there are seven possible AC coupled combinations where 1149.1 will not work as compared to only three DC coupled combinations where 1149.1 will work. As the quest for higher signal speeds continues in the future, the use of AC coupling will increase. This becomes especially true with the development of optical communication signals. The consequence will be less and less reliance on conventional 1149.1 testing.

A definite need exists for a boundary scan testing means for AC coupled interconnections that builds on the advantages of conventional 1149.1 testing. Specifically, a need exists for a boundary scan testing means which is capable of testing both DC and AC coupled interconnections. Ideally, such a testing means would be backward compatible, robust, and inexpensive. A primary purpose of the present invention is to solve these needs and provide further, related advantages.

BRIEF DESCRIPTION OF THE INVENTION

A system for and method of testing AC coupled interconnects using boundary scan test methodology is disclosed. Specially designed AC boundary scan cells and boundary scan logic are used. These are intended to be compatible with conventional

5 IEEE Standard 1149.1 testing. A method known as *AC\_EXTEST* is used to determine the reliability of the AC coupled interconnections. The method includes preloading the test stimulus, initiating the *AC\_EXTEST* instruction, executing the *AC\_EXTEST* instruction, transferring the *AC\_EXTEST* instruction results, and evaluating the *AC\_EXTEST* results.

10 During the test, the TAP controller of both the driving IC and the receiving IC is held in the *Run-Test/Idle* state for the time required to complete execution of the instruction.

During this controller state, the driving IC is applying the AC test stimulus to the interconnections and the receiving IC is sampling the signal. The test may be repeated with different test data and may be run together with a conventional DC *EXTEST* method to determine the reliability of both the AC and the DC coupled interconnections

15 independently.

### BRIEF DESCRIPTION OF THE DRAWINGS

The accompanying drawings, which are incorporated into and constitute a part of this specification, illustrate one or more embodiments of the present invention and, together with the detailed description, serve to explain the principles and implementations of the invention.

In the drawings:

FIG. 1 is a detailed logic block diagram of a prior art BSC;

FIG. 2 is a detailed logic block diagram of a prior art bi-directional BSC;

FIG. 3 is a block diagram of ten possible combinations of DC and AC coupled interconnections between two devices;

FIG. 4 is a logic flow diagram of the *AC\_EXTEST* test method;

FIG. 5 shows two example timing diagrams for some of the signals used in the *AC\_EXTEST* method;

FIG. 6 is a detailed logic block diagram of an *AC\_Test\_Marker* signal generator;

FIG. 7 is a detailed logic block diagram of an *AC\_Pattern\_Source* signal generator;

FIG. 8 is a detailed logic block diagram of an *AC\_Test\_Ran* signal generator;

FIG. 9 is a detailed logic block diagram of an AC BSC according to one embodiment of the present invention;

FIG. 10 is a detailed logic block diagram of an AC BSC according to one embodiment of the present invention;

FIG. 11 is a detailed logic block diagram of an AC BSC according to one embodiment of the present invention;

FIG. 13 is a detailed logic block diagram of an input AC BSC according to one embodiment of the present invention;

FIG. 15 is a detailed logic block diagram of a bi-directional AC BSC according to one embodiment of the present invention; and

FIG. 16 is a detailed logic block diagram of a bi-directional AC BSC according to one embodiment of the present invention.

### DETAILED DESCRIPTION

Embodiments of the present invention are described herein in the context of AC coupled line testing using boundary scan test methodology. Those of ordinary skill in the art will realize that the following detailed description of the present invention is

5 illustrative only and is not intended to be in any way limiting. Other embodiments of the present invention will readily suggest themselves to such skilled persons having the benefit of this disclosure. Reference will now be made in detail to implementations of the present invention as illustrated in the accompanying drawings. The same reference indicators will be used throughout the drawings and the following detailed description to  
10 refer to the same or like parts.

In the interest of clarity, not all of the routine features of the implementations described herein are shown and described. It will, of course, be appreciated that in the development of any such actual implementation, numerous implementation-specific  
15 decisions must be made in order to achieve the specific goals of the developer, such as compliance with application- and business-related constraints, and that these specific goals will vary from one implementation to another and from one developer to another. Moreover, it will be appreciated that such a development effort might be complex and time-consuming, but would nevertheless be a routine undertaking of engineering for  
20 those of ordinary skill in the art having the benefit of this disclosure.

To the extent applicable, in accordance with the present invention, the components, process steps, and/or data structures may be implemented using various

types of operating systems, computing platforms, computer programs, and/or general purpose machines. In addition, those of ordinary skill in the art will recognize that devices of a less general purpose nature, such as hardwired devices, field programmable gate arrays (FPGAs), application specific integrated circuits (ASICs), or the like, may also be used without departing from the scope and spirit of the inventive concepts disclosed herein.

Included among the various testing methods of conventional 1149.1 boundary scan logic is one known as *EXTEST*. During the *EXTEST* method, a value, either logic one or logic zero, is loaded onto the latched parallel outputs of the update data registers of the BSCs of the driving IC using a *PRELOAD* instruction or is loaded with a *ShiftDR* state while the IC is in the *EXTEST* instruction. The value being driven is then sampled by the input BSCs of the receiving IC when the TAP controller passes through a *CaptureDR* state. Finally, by serially shifting out and examining the captured values, one can determine the reliability of the interconnections. This process assumes that the logic value during the time of capture is a static DC value. As noted above, this assumption only holds if the interconnections are DC coupled. As a result, the *EXTEST* method fails to test AC coupled interconnections.

To address the failure of conventional 1149.1 boundary scan logic in general and the *EXTEST* method more specifically, the following design specification was developed. In order to deal with AC coupled interconnections, it was necessary to change both the boundary scan logic and the BSCs themselves. Nevertheless, every effort was made to

design the changes to be backward compatible with conventional testing. As a result, most of the details which are not outlined here are the same as those for conventional testing. For reference purposes, the testing method is known as *AC\_EXTEST* and the BSCs are known as AC or AC capable BSCs. All of the BSCs outlined below are AC

5 BSCs whether or not they are specifically identified as such.

Turning now to FIG. 4, a logic flow diagram of the *AC\_EXTEST* test method is shown. In the interest of clarity, it will be assumed that the method is being performed on a circuit only having one driving IC and one receiving IC that are couple together by

10 at least one AC interconnection. The principles disclosed below can easily be extrapolated to larger circuits by one of ordinary skill in the art. At block 32, an AC test stimulus is shifted into the BSCs of the driving IC using the *PRELOAD* instruction. At block 34, an initiate *AC\_EXTEST* instruction is scanned into the instruction register of both ICs. Taken together, blocks 32 and 34 prepare the ICs for their respective test roles.

15 At block 36, an execute *AC\_EXTEST* instruction is performed by moving the TAP controller to the *Run-Test/Idle* state. The TAP controller of both ICs is held in the *Run-Test/Idle* state for the time required to complete execution of the instruction. During this controller state, the driving IC is applying the AC test stimulus to the interconnections and the receiving IC is sampling the signal. The form and timing of the various signals

20 will be discussed further with respect to FIG. 5 below. At block 38, the *AC\_EXTEST* instruction results are transferred into the BSCs of the receiving IC from the sampled value. This occurs when the TAP controller passes from the *Run-Test/Idle* state to the *CaptureDR* state. At block 40, the *AC\_EXTEST* results are evaluated. The captured

results are scanned out in a conventional manner by placing the TAP controller in the *ShiftDR* state. As with the *EXTEST* above, the scanned results are evaluated to determine the reliability of the AC coupled interconnections. At block 41, new test data may be loaded and blocks 36 through 40 repeated. For example, this enables different test data to be used for one test run for logic one and one for logic zero. The *AC\_EXTEST* method may be run independently or together with the DC *EXTEST* method to determine the reliability of both the AC and the DC coupled interconnections independently.

Turning now to FIG. 5, two example timing diagrams for some of the signals used in the *AC\_EXTEST* method are shown. One group of signals has been labeled collectively as X1, that is, times one, and labeled individually as either 1 or A. The other group of signals has been labeled collectively as X2, that is, times two of those of group X1, and labeled individually as either 2 or B. The *Run-Test/Idle* signal is independent of either group. Recall from above that the *AC\_EXTEST* method executes when the *Run-Test/Idle* signal is high. The *TCK* signal is a clock signal that may be either the boundary scan clock signal or another clock, such as a *AC\_Pattern\_Clock* signal, running at a higher rate. Example *AC\_Pattern* signals are shown for logic one and logic zero. The *AC\_Sync* signal goes high every sixteenth clock cycle on the falling edge of the clock cycle. It is at this time that the receiving IC samples the test stimulus as discussed above. The generation and use of the *AC\_Sync* signal may not be necessary depending on the circumstances outlined below. Actual *AC\_Pattern* signals may differ from the examples shown. In any case, the logic value of the *AC\_Pattern* signals at the time when the



*AC\_Sync* signal is occurring should be the same value as the latched parallel output of the update register value of the AC BSC.

There are other signals used in the *AC\_EXTEST* method that are not shown in FIG. 5. Some of the signals are conventional signals that have simply been relabeled, such as *Mode* to *DC\_Mode*, to better identify them or to distinguish them from new and existing signals. Others are new signals such as an *AC\_Test* signal which becomes true when the TAP controller is in the *Run-Test/Idle* state with the execute *AC\_EXTEST* instruction loaded in the instruction register.

Turning now to FIG. 6, a detailed logic block diagram of an *AC\_Test\_Marker* signal generator 42 is shown. The generator 42 includes a first shift register 44, a second shift register 46, a third shift register 48, an AND gate 50, and an OR gate 52. The generator 42 has as inputs an *AC\_Test* signal line and an *AC\_Pattern\_Clock* signal line and has as an output an *AC\_Test\_Marker* signal line. The various lines and circuit elements are coupled to one another as shown. The *AC\_Test\_Marker* signal is a single event, one and one half *AC\_Pattern\_Clock* cycle long, and positive going pulse to mark the beginning of the *AC\_Pattern* signal sequences. The extra one half cycle acts to block any unwanted problems caused by changing *TCK* during the *AC\_Pattern\_Clock* switching.

Turning now to FIG. 7, a detailed logic block diagram of an *AC\_Pattern\_Source* signal generator 54 is shown. The generator 54 includes a shift register 56. The

generator 54 has as inputs an *AC\_Test\_Marker* signal line and an *AC\_Pattern\_Clock* signal line and has as an output an *AC\_Pattern\_Source* signal line. The various lines are coupled as shown. The *AC\_Test\_Marker* signal is used to set the shift register 56 to a known value. Subsequently, the *AC\_Pattern\_Clock* signal becomes the

5 *AC\_Pattern\_Source* signal and is used to generate appropriate signal pattern sequences for each BSC depending on the value stored in the respective update data register.

Turning now to FIG. 8, a detailed logic block diagram of an *AC\_Test\_Ran* signal generator 58 is shown. The generator 58 includes a shift register 60. The generator 58

10 has as inputs an *AC\_Test\_Marker* signal line, a *Logic Low* signal line, an *UpdateDR* signal line, and a *Reset* signal line and has as an output an *AC\_Test\_Ran* signal line. The various lines are coupled as shown. The *AC\_Test\_Marker* signal is used to set the shift register 60 to a known value. For example, setting the value to a logic one signifies that the execute *AC\_EXTEST* instruction is being or was previously loaded in the instruction

15 register with the TAP controller in the *Run-Test/Idle* state. The value is cleared when the *UpdateDR* signal or the *Reset* signal is received signifying that the execute *AC\_EXTEST* instruction has been performed and that the TAP controller has been placed into the *CaptureDR* and subsequent *UpdateDR* states. With the *AC\_Test\_Ran* signal one can perform DC *EXTEST* functions with the *AC\_EXTEST* instructions when the

20 *AC\_Test\_Ran* signal is not set.

Under the *AC\_EXTEST* method, the signals outlined above, among others, a modified AC TAP controller, and the AC BSCs outlined below are utilized to add AC

coupled line testing capability to the conventional boundary scan logic. Several AC BSCs will be disclosed. One of ordinary skill in the art will realize that any combination of AC and DC BSCs may be used depending on the circumstances.

5           Turning now to FIG. 9, a detailed logic block diagram of an AC BSC 62 according to one embodiment of the present invention is shown. The BSC 62 includes a first multiplexer 64, a second multiplexer 66, a first data shift register 68, a second data register 70, a XOR logic gate 72, and a third multiplexer 74. As above, the BSC 62 includes an SDI line, an SDO line, a TDI line, a TDO line, a *ShiftDR* signal input line, an  
10 *AC\_Pattern\_Clock* or *ClockDR* signal input line, an *UpdateDR* signal input line, and a *Mode* signal input line, shown here as *DC\_Mode*. In addition, the BSC 62 includes an *AC\_Pattern\_Source* signal input line and an *AC\_Test* signal input line. Each line is coupled to receive the corresponding signal from the boundary scan logic. The various lines and circuit elements are coupled to one another as shown. The *AC\_Pattern\_Clock*  
15 signal is a shared clock signal for AC pattern generation and for capturing and shifting boundary scan test signals. The latter function is similar to the conventional *ClockDR* signal. The *AC\_Pattern\_Source* signal is used directly without inversion when the second data register 70 has a test value of logic one and is used after inversion when the second data register 70 has a test value of logic zero. The function of logic inversion is  
20 accomplished by the use of the XOR gate 72.

Turning now to FIG. 10, a detailed logic block diagram of an AC BSC 76 according to one embodiment of the present invention is shown. The BSC 76 includes a

first multiplexer 78, a second multiplexer 80, a third multiplexer 82, a first data shift register 84, a fourth multiplexer 86, a second data register 88, and a fifth multiplexer 90.

As above, the BSC 76 includes an SDI line, an SDO line, a TDI line, a TDO line, a *ShiftDR* signal input line, an *AC\_Test* signal input line, a *AC\_Pattern\_Clock* or *ClockDR*

5 signal input line, an *UpdateDR* signal input line, and a *DC\_Mode* signal input line. In addition, the BSC 76 includes an *AC\_Test\_Marker* signal input line. Each line is coupled to receive the corresponding signal from the boundary scan logic. The various lines and circuit elements are coupled to one another as shown. In this embodiment, the BSC 76 has a built-in AC pattern generator. First the output value Q from the second data  
10 register 88 is copied into the input D of the first data shift register 84 using the *AC\_Test\_Marker* signal and the *AC\_Pattern\_Clock* signal. Subsequently, the *AC\_Pattern\_Clock* signal starts to generate the AC patterns for testing. After the initial copy of data register 88 is made, the third multiplexer 82 selects the Q bar output of the first data shift register 84, thus enabling the first data shift register 84 to toggle the value  
15 every *AC\_Pattern\_Clock* cycle.

Turning now to FIG. 11, a detailed logic block diagram of an AC BSC 92 according to one embodiment of the present invention is shown. The BSC 92 includes a first multiplexer 94, a second multiplexer 96, a third multiplexer 98, a first data shift  
20 register 100, a second data register 102, a XOR logic gate 104, and a fourth multiplexer 106. As above, the BSC 92 includes an SDI line, an SDO line, a TDI line, a TDO line, an *AC\_Test\_Marker* signal input line, a *ShiftDR* signal input line, an *AC\_Test* signal input line, an *AC\_Pattern\_Clock* or *ClockDR* signal input line, an *UpdateDR* signal input line,

and a *DC\_Mode* signal input line. Each line is coupled to receive the corresponding signal from the boundary scan logic. The various lines and circuit elements are coupled to one another as shown. As with the BSC 76 of FIG. 10, the BSC 92 has a built-in AC pattern generator. However, in this embodiment, the *AC\_Test\_Marker* signal is used to  
5 set the first data shift register 100 into a known state before generating the AC patterns.

Turning now to FIG. 12, a detailed logic block diagram of an input AC BSC 108 according to one embodiment of the present invention is shown. The BSC 108 includes a first multiplexer 110, a first data shift register 112, a second multiplexer 114, a third  
10 multiplexer 116, a second data register 118, and a third data shift register 120. In this embodiment, the BSC 108 is an input scan cell so it includes an SDRI line instead of an SDI line and an SDRO line instead of and SDO line. As above, the BSC 108 includes a TDI line, a TDO line, a *ShiftDR* signal input line, a *ClockDR* signal input line, an *UpdateDR* signal input line, and a *DC\_Mode* signal input line. In addition, the BSC 108  
15 includes an *AC\_Sync* signal input line and an *AC\_Test\_Ran* signal input line. Each line is coupled to receive the corresponding signal from the boundary scan logic. The various lines and circuit elements are coupled to one another as shown. In the BSC 108, when the *AC\_Test\_Ran* signal becomes active, signifying that the execute *AC\_EXTEST* instruction was loaded in the instruction register with the TAP controller is in the *Run-*  
20 *Test/Idle* state, the second data register 118 captures sampled AC pattern values from the first data shift register 112 which is responsive to the *AC\_Sync* signal. When the *AC\_Test\_Ran* signal is not active, the second data register 118 captures values from the SDRI line signifying that the test was either *DC\_EXTEST* or *AC\_EXTEST* without passing

through the *Run-Test/Idle* controller state. This ensures compatibility with the existing DC *EXTEST* method.

Turning now to FIG. 13, a detailed logic block diagram of an input AC BSC 122 according to one embodiment of the present invention is shown. The BSC 122 includes a first data shift register 124, a first multiplexer 126, a second multiplexer 128, and a second data register 130. As with the BSC 108 of FIG. 12, the BSC 122 is an input scan cell so it includes an SDRI line and an SDRO line. However, in this embodiment, the BSC 122 is an observe only input scan cell so there is no bisecting of the SDRI line from the SDRO line. As above, the BSC 122 includes a TDI line, a TDO line, an *AC\_Sync* signal input line, an *AC\_Test\_Ran* signal input line, a *ShiftDR* signal input line, and a *ClockDR* signal input line. Each line is coupled to receive the corresponding signal from the boundary scan logic. The various lines and circuit elements are coupled to one another as shown.

Turning now to FIG. 14, a detailed logic block diagram of a bi-directional AC BSC 132 according to one embodiment of the present invention is shown. In addition to the BSC 132, an output buffer 134, an input buffer 136, an I/O pin 138, and a control cell 140 are shown for greater clarity. The control cell 140 is similar to the BSC 10 of FIG. 1. The BSC 132 includes an output cell 142 and an input cell 144. The output cell 142 is similar to the BSC 62 of FIG. 9. The input cell 144 is similar to the BSC 122 of FIG. 13. Since the BSC 132 is bi-directional, it has each of an SDI line, an SDO line, an SDRI line, and an SDRO line. As always, the BSC 132 has a TDI line and a TDO line. Each

line is coupled to receive the corresponding signal from the boundary scan logic. The various lines and circuit elements are coupled to one another as shown.

Turning now to FIG. 15, a detailed logic block diagram of a bi-directional AC BSC 146 according to one embodiment of the present invention is shown. As above, the output buffer 134, the input buffer 136, and the I/O pin 138 are shown for greater clarity. In this case, a different control cell 148 is shown. The control cell 148 is of conventional design as shown. The BSC 146 includes a first multiplexer 150, a first data shift register 152, a second multiplexer 154, a third multiplexer 156, a second data register 158, a third data shift register 160, a XOR logic gate 162, and a fourth multiplexer 164. As above, the BSC 146 has an SDI line, an SDO line, an SDRI line, an SDRO line, a TDI line, and a TDO line. The BSC 146 also includes a *Mode* signal input line, an *AC\_Test\_Ran* signal input line, an *AC\_Sync* signal input line, a *ShiftDR* signal input line, a *ClockDR* signal input line, an *UpdateDR* signal input line, an *AC\_Pattern\_Source* signal input line, and an *AC\_Test* signal input line. Each line is coupled to receive the corresponding signal from the boundary scan logic. The various lines and circuit elements are coupled to one another as shown.

Turning now to FIG. 16, a detailed logic block diagram of a bi-directional AC BSC 166 according to one embodiment of the present invention is shown. As above, the output buffer 134, the input buffer 136, the I/O pin 138, and the control cell 148 are shown for greater clarity. As above, the control cell 148 is of conventional design. In addition, an AND logic gate 168 is shown having a *Mode\_3* signal input line coupled to a

first input. The BSC 166 includes a first multiplexer 170, a second multiplexer 172, a first data shift register 174, an AND logic gate 176 with one input inverted, a third multiplexer 178, a fourth multiplexer 180, a fifth multiplexer 182, a second data register 184, a third data register 186, a XOR logic gate 188, and a sixth multiplexer 190. As  
5 above, the BSC 166 has an SDI line, an SDO line, an SDRI line, an SDRO line, a TDI line, a TDO line, an *AC\_Sync* signal input line, an *AC\_Test\_Ran* signal input line, a *ShiftDR* signal input line, a *ClockDR* signal input line, an *UpdateDR* signal input line, an *AC\_Pattern\_Source* signal input line, and an *AC\_Test* signal input line. In addition, the BSC 166 includes a *Mode\_1* signal input line and a *Mode\_2* signal input line. Each line  
10 is coupled to receive the corresponding signal from the boundary scan logic. The various lines and circuit elements are coupled to one another as shown.

An *AC\_Test* signal and an *AC\_Test\_Ran* signal can be gated with the update data register of other BSCs to force the signals into an inactive state. In this application, BSCs  
15 used to disable an *AC\_Test* signal or an *AC\_Test\_Ran* signal are *AC\_EXTEST* control cells which are referred to as a type "INTERNAL" in function element value under the Boundary Scan Description Language register description section. With this functionality, one can selectively disable or enable a group or individual AC BSCs from performing *AC\_EXTEST* by loading an appropriate value into the *AC\_EXTEST* control  
20 cell.

While embodiments and applications of this invention have been shown and described, it would be apparent to those skilled in the art having the benefit of this



[illegible]